

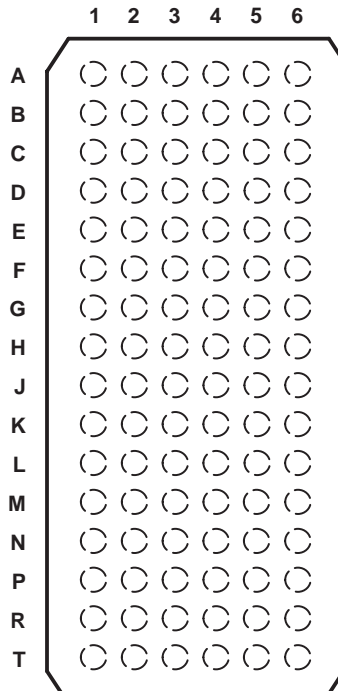
# SN74LVTH32244

## 3.3-V ABT 32-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCBS749A – OCTOBER 2000 – REVISED SEPTEMBER 2003

- Member of the Texas Instruments Widebus+™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Typical  $V_{OLP}$  (Output Ground Bounce)  $<0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  and Power-Up 3-State Support Hot Insertion
- Supports Unregulated Battery Operation Down to 2.7 V
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V  $V_{CC}$ )
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

GKE OR ZKE PACKAGE  
(TOP VIEW)



terminal assignments

	1	2	3	4	5	6
A	1Y2	1Y1	$\overline{1OE}$	$\overline{2OE}$	1A1	1A2
B	1Y4	1Y3	GND	GND	1A3	1A4
C	2Y2	2Y1	$1V_{CC}$	$1V_{CC}$	2A1	2A2
D	2Y2	2Y3	GND	GND	2A3	2A4
E	3Y2	3Y1	GND	GND	3A1	3A2
F	3Y4	3Y3	$1V_{CC}$	$1V_{CC}$	3A3	3A4
G	4Y2	4Y1	GND	GND	4A1	4A2
H	4Y3	4Y4	$\overline{4OE}$	$\overline{3OE}$	4A4	4A3
J	5Y2	5Y1	$\overline{5OE}$	$\overline{6OE}$	5A1	5A2
K	5Y4	5Y3	GND	GND	5A3	5A4
L	6Y2	6Y1	$2V_{CC}$	$2V_{CC}$	6A1	6A2
M	6Y4	6Y3	GND	GND	6A3	6A4
N	7Y2	7Y1	GND	GND	7A1	7A2
P	7Y4	7Y3	$2V_{CC}$	$2V_{CC}$	7A3	7A4
R	8Y2	8Y1	GND	GND	8A1	8A2
T	8Y3	8Y4	$\overline{8OE}$	$\overline{7OE}$	8A4	8A3

### description/ordering information

#### ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
$-40^\circ\text{C}$ to $85^\circ\text{C}$	LFBGA – GKE	Tape and reel	SN74LVTH32244GKER	HV244
	LFBGA – ZKE (Pb-free)		SN74LVTH32244ZKER	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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## 3.3-V ABT 32-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS

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### description/ordering information (continued)

The SN74LVTH32244 is a 32-bit buffer and line driver designed for low-voltage (3.3-V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment. This device can be used as eight 4-bit buffers, four 8-bit buffers, two 16-bit buffers, or one 32-bit buffer. The device provides true outputs and has symmetrical active-low output-enable ( $\overline{OE}$ ) inputs. It is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

When  $V_{CC}$  is between 0 and 1.5-V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5-V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

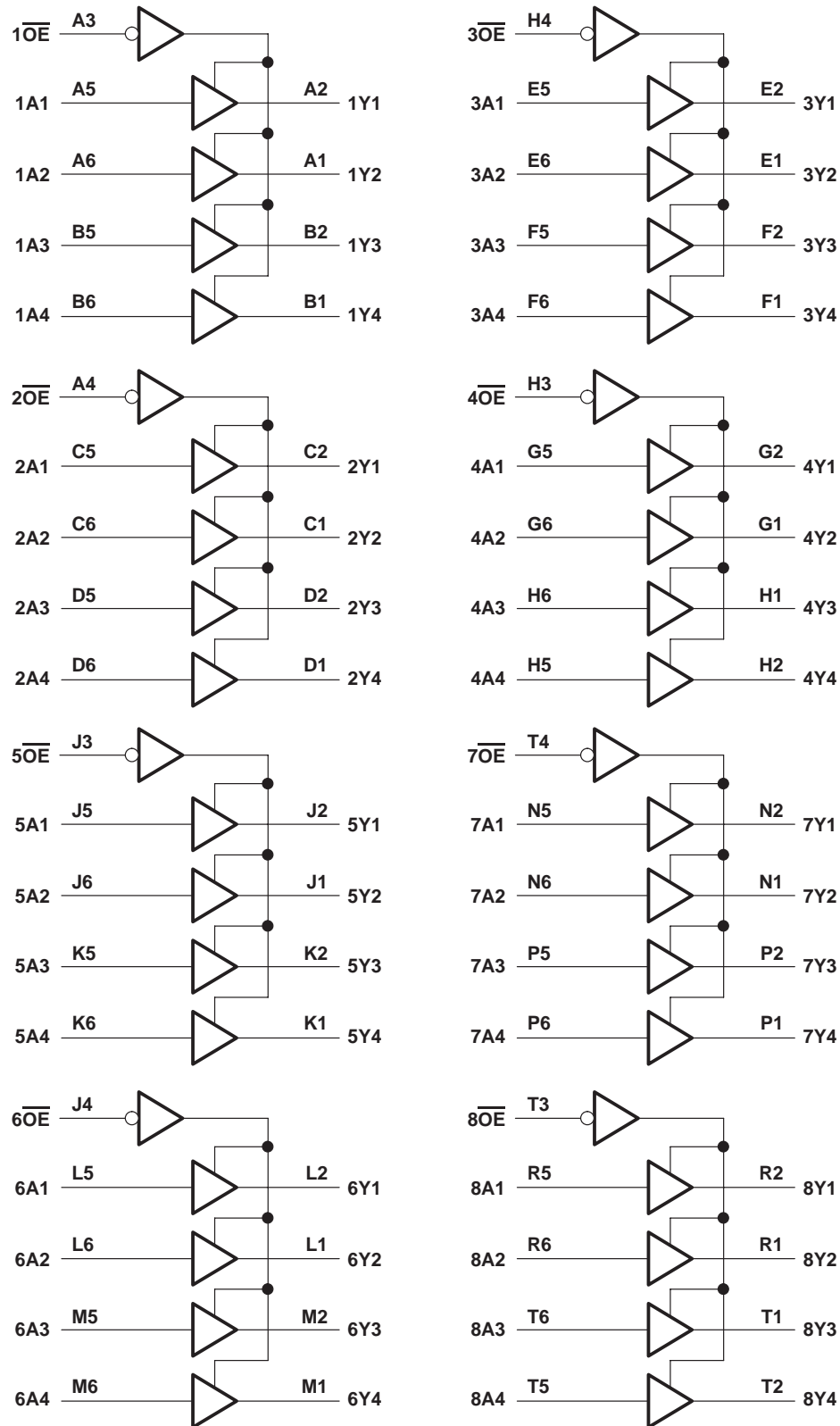
**FUNCTION TABLE**  
(each 4-bit buffer/driver)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

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logic diagram (positive logic)



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## 3.3-V ABT 32-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	–0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, $V_O$ (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, $I_O$	128 mA
Current into any output in the high state, $I_O$ (see Note 2)	64 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): GKE/ZKE package	40°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .  
3. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 4)

	MIN	MAX	UNIT
$V_{CC}$ Supply voltage	2.7	3.6	V
$V_{IH}$ High-level input voltage	2		V
$V_{IL}$ Low-level input voltage		0.8	V
$V_I$ Input voltage		5.5	V
$I_{OH}$ High-level output current		–32	mA
$I_{OL}$ Low-level output current		64	mA
$\Delta t/\Delta v$ Input transition rise or fall rate		10	ns/V
$\Delta t/\Delta V_{CC}$ Power-up ramp rate	200		μs/V
$T_A$ Operating free-air temperature	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V <sub>IK</sub>		V <sub>CC</sub> = 2.7 V, I <sub>I</sub> = −18 mA				−1.2	V
V <sub>OH</sub>		V <sub>CC</sub> = 2.7 V to 3.6 V, I <sub>OH</sub> = −100 μA		V <sub>CC</sub> −0.2			V
		V <sub>CC</sub> = 2.7 V, I <sub>OH</sub> = −8 mA		2.4			
		V <sub>CC</sub> = 3 V, I <sub>OH</sub> = −32 mA		2			
V <sub>OL</sub>		V <sub>CC</sub> = 2.7 V	I <sub>OL</sub> = 100 μA			0.2	V
			I <sub>OL</sub> = 24 mA			0.5	
		V <sub>CC</sub> = 3 V	I <sub>OL</sub> = 16 mA			0.4	
			I <sub>OL</sub> = 32 mA			0.5	
			I <sub>OL</sub> = 64 mA			0.55	
I <sub>I</sub>		V <sub>CC</sub> = 0 or 3.6 V, V <sub>I</sub> = 5.5 V			10	μA	
	Control inputs	V <sub>CC</sub> = 3.6 V, V <sub>I</sub> = V <sub>CC</sub> or GND			±1		
	Data inputs	V <sub>CC</sub> = 3.6 V	V <sub>I</sub> = V <sub>CC</sub>				1
			V <sub>I</sub> = 0				−5
I <sub>off</sub>		V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> = 0 to 4.5 V			±100	μA	
I <sub>I</sub> (hold)	Data inputs	V <sub>CC</sub> = 3 V	V <sub>I</sub> = 0.8 V	75			μA
			V <sub>I</sub> = 2 V	−75			
		V <sub>CC</sub> = 3.6 V‡, V <sub>I</sub> = 0 to 3.6 V	±500				
I <sub>OZH</sub>		V <sub>CC</sub> = 3.6 V, V <sub>O</sub> = 3 V			5	μA	
I <sub>OZL</sub>		V <sub>CC</sub> = 3.6 V, V <sub>O</sub> = 0.5 V			−5	μA	
I <sub>OZPU</sub>		V <sub>CC</sub> = 0 to 1.5 V, V <sub>O</sub> = 0.5 V to 3 V, $\overline{OE}$ = don't care				±100	μA
I <sub>OZPD</sub>		V <sub>CC</sub> = 1.5 V to 0, V <sub>O</sub> = 0.5 V to 3 V, $\overline{OE}$ = don't care				±100	μA
I <sub>CC</sub>		V <sub>CC</sub> = 3.6 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs high			0.38	mA
			Outputs low			10	
			Outputs disabled			0.38	
ΔI <sub>CC</sub> §		V <sub>CC</sub> = 3 V to 3.6 V, One input at V <sub>CC</sub> − 0.6 V, Other inputs at V <sub>CC</sub> or GND				0.2	mA
C <sub>i</sub>		V <sub>I</sub> = 3 V or 0				4	pF
C <sub>o</sub>		V <sub>O</sub> = 3 V or 0				9	pF

† All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

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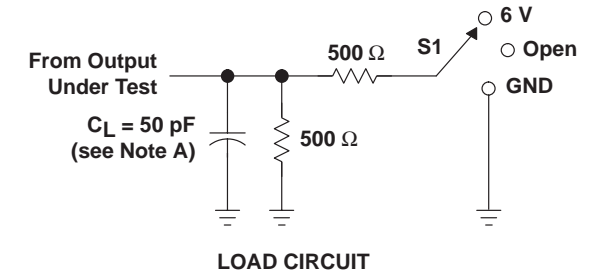
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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

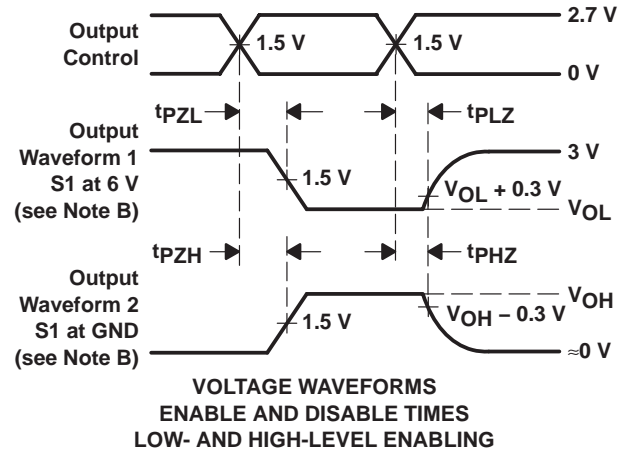
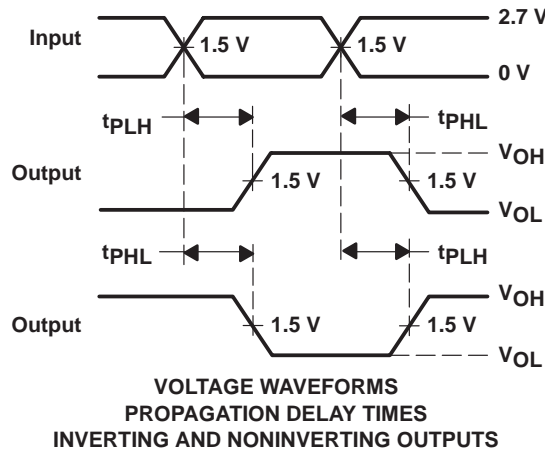
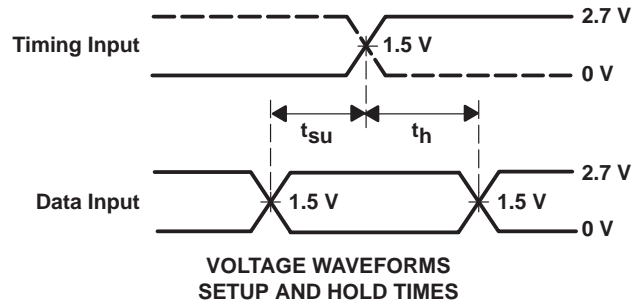
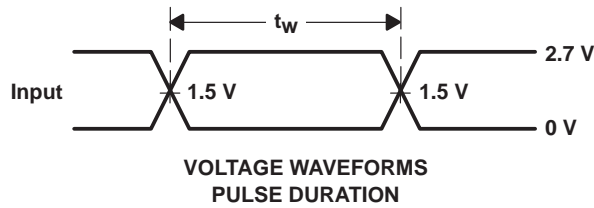
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 3.3 V ± 0.3 V			V <sub>CC</sub> = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	1.2	2.3	3.2	3.7		ns
t <sub>PHL</sub>			1.2	2	3.2	3.7		
t <sub>PZH</sub>	$\overline{OE}$	Y	1.2	2.6	4	5		ns
t <sub>PZL</sub>			1.2	2.7	4	5		
t <sub>PHZ</sub>	$\overline{OE}$	Y	2.2	3.3	4.5	5		ns
t <sub>PLZ</sub>			2	3.1	4.2	4.4		
t <sub>sk(o)</sub>			0.5					ns

† All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

## PARAMETER MEASUREMENT INFORMATION



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND

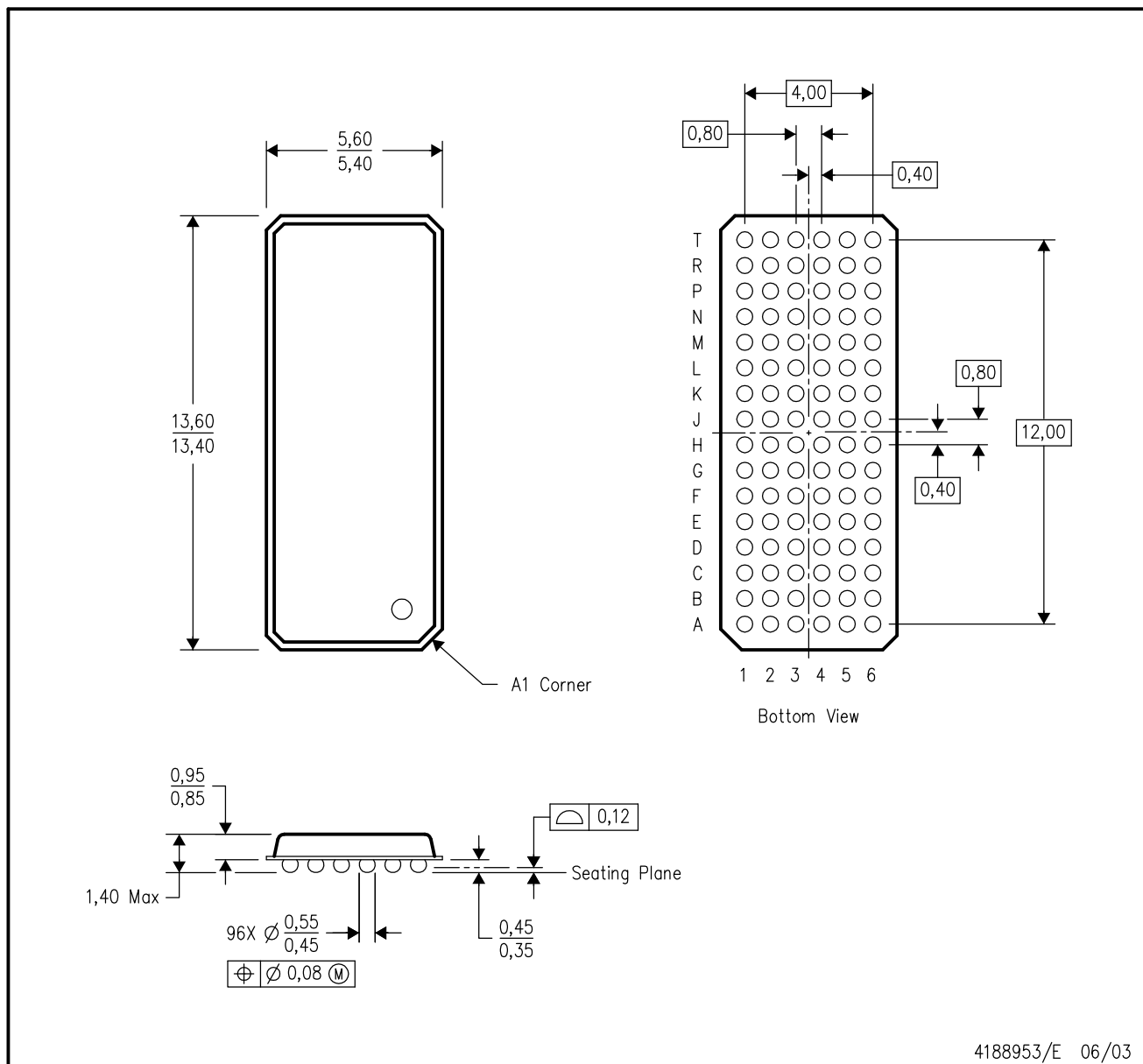


- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.  
 D. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

## GKE (R-PBGA-N96)

## PLASTIC BALL GRID ARRAY



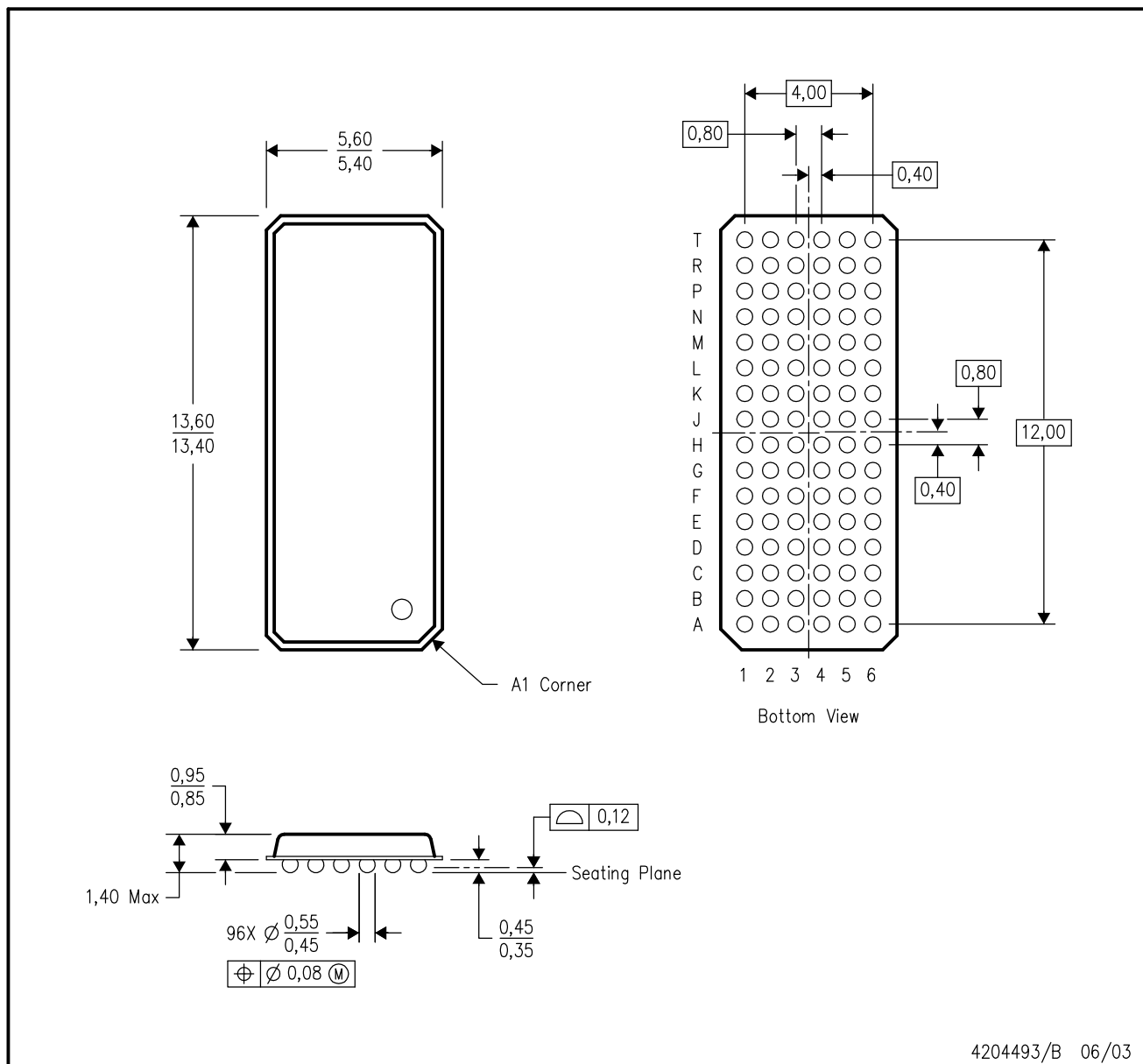
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. MicroStar BGA™ configuration
  - D. Falls within JEDEC MO-205 variation CC.
  - E. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.

MicroStar BGA is a trademark of Texas Instruments.



## ZKE (R-PBGA-N96)

## PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. MicroStar BGA™ configuration
  - D. Falls within JEDEC MO-205 variation CC.
  - E. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).

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